# Applications Note:AN_SY8105

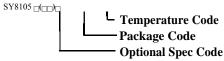## High Efficiency, 500kHz, 5A, 18V Input Synchronous Step Down Regulator

## General Description

The SY8105 is a high efficiency 500 kHz synchronous step-down DC-DC converter capable of delivering 5.0A current. The SY8105 operates over a wide input voltage range from 4.5V to 18V and integrates main switch and synchronous switch with very low $R_{DS(ON)}$ to minimize the conduction loss.

Low output voltage ripple and small external inductor and capacitor sizes are achieved with 500 kHz switching frequency. It adopts the instant PWM architecture to achieve fast transient responses for high step down applications

## Ordering Information

SY8105 □(□□)□

    └ **Temperature Code**
    — **Package Code**
    — **Optional Spec Code**

| Ordering Number | Package type | Note |
|---|---|---|
| SY8105ADC | TSOT23-6 | -- |

## Features

- low $R_{DS(ON)}$ for internal switches (top/bottom): 40mΩ/26mΩ
- 4.5-18V input voltage range
- 5.0A output current capability
- 500 kHz switching frequency
- Instant PWM architecture to achieve fast transient responses.
- Internal softstart limits the inrush current
- Cycle-by-cycle peak current limitation
- 1.5% 0.6V reference
- TSOT23-6 package

## Applications

- Set Top Box
- Portable TV
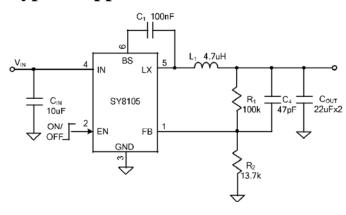- Access Point Router
- DSL Modem
- LCD TV
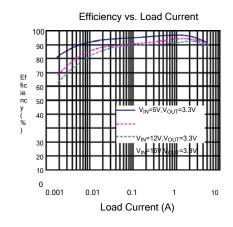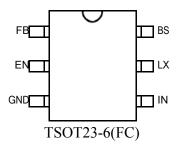
## Typical Applications



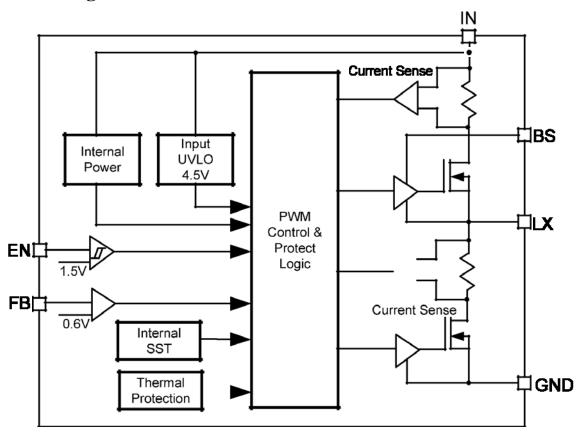**Figure 1. Schematic Diagram**



**Figure 2. Schematic Diagram**

## Pinout (top view)

```
        _____
FB  ┌──┤  ⌣        ├──┐  BS
    └──┤           ├──┘
EN  ┌──┤           ├──┐  LX
    └──┤           ├──┘
GND ┌──┤           ├──┐  IN
    └──┤_____├──┘
```

TSOT23-6(FC)

Top Mark: **NY**xyz, (Device code: NY, *x=year code, y=week code, z= lot number code*)

| Pin Name | Pin Number | Pin Description |
|---|---|---|
| FB | 1 | Output Feedback Pin. Connect this pin to the center point of the output resistor divider (as shown in Figure 1) to program the output voltage: Vout=0.6*(1+R1/R2) |
| EN | 2 | Enable control. Pull high to turn on. Do not float. |
| GND | 3 | Ground pin |
| IN | 4 | Input pin. Decouple this pin to GND pin with at least 1uF ceramic cap |
| LX | 5 | Inductor pin. Connect this pin to the switching node of inductor |
| BS | 6 | Boot-Strap Pin. Supply high side gate driver. Decouple this pin to LX pin with 0.1uF ceramic cap. |

## Absolute Maximum Ratings (No e 1)

Supply Input Voltage ------------------------------------------------------------------------------------- 19V
Enable Voltage----------------------------------------------------------------------------------------- VIN + 0.3V
FB Voltage ------------------------------------------------------------------------------------------ 4V
Power Dissipation, PD @ TA = 25°C, TSOT23-6（FC） ------------------------------------------- 1.75W
  Package Thermal Resistance (Note 2)
  $\theta_{JA}$ ------------------------------------------------------------------------------------- 56°C /W
  $\theta_{JC}$ ------------------------------------------------------------------------------------- 6.3°C /W
Junction Temperature Range --------------------------------------------------------------------------- 125°C
Lead Temperature (Solde ing, 10 sec.) ----------------------------------------------------------------- 260°C
  Storage Temperature Range ------------------------------------------------------------------ - 65°C to 150°C

## Recommended Operating Conditions (Note 3)

Supply Input Voltage ---------------------------------------------------------------------------- 4.5V to 18V
  Junction Temperature Range ------------------------------------------------------------------- - 40°C to 125°C
  Ambient Temperature Range -------------------------------------------------------------------- - 40°C to 85°C

## Block Diagram

## Electrical Characteristics

($V_{IN}$ = 12V, $V_{OUT}$ = 1.2V, L = 2.2uH, $C_{OUT}$ = 47uF, $T_A$ = 25°C, $I_{OUT}$ = 1A unless otherwise specified)

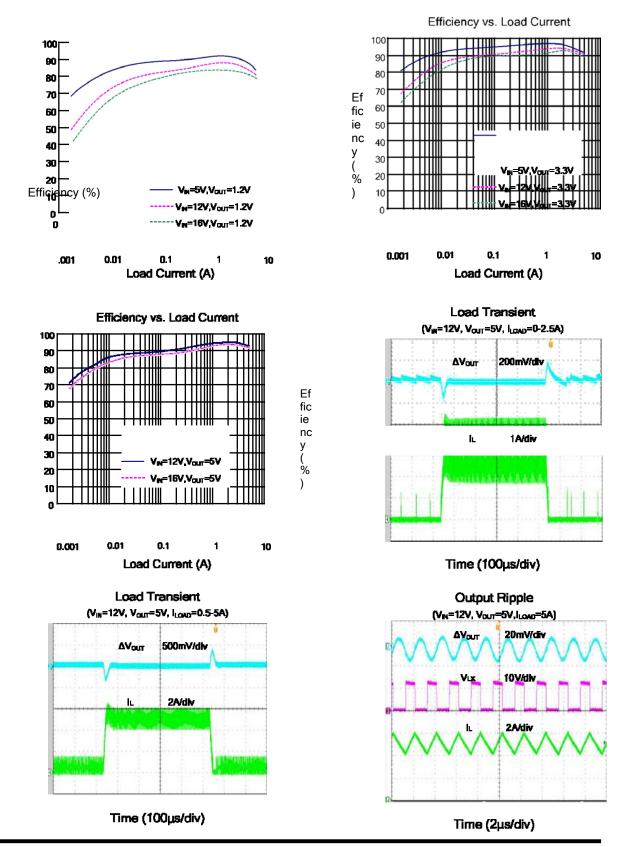| Parameter | Symbol | Test Conditions | Min | Typ | Max | Unit |
|---|---|---|---|---|---|---|
| Input Voltage Range | $V_{IN}$ | | 4.5 | | 18 | V |
| Quiescent Current | $I_Q$ | $I_{OUT}$=0, $V_{FB}$=$V_{REF}$*105% | | 100 | | μA |
| Shutdown Current | $I_{SHDN}$ | EN=0 | | 5 | 10 | μA |
| Feedback Reference Voltage | $V_{REF}$ | | 0.591 | 0.6 | 0.609 | V |
| FB Input Current | $I_{FB}$ | $V_{FB}$=3.3V | -50 | | 50 | nA |
| Top FET RON | $R_{DS(ON)1}$ | | | 40 | | mΩ |
| Bottom FET RON | $R_{DS(ON)2}$ | | | 20 | | mΩ |
| TOP FET Peak Current Limit | $I_{LIM,TOP}$ | | | | 10 | A |
| Bottom FET Valley Current Limit | $I_{LIM,BOTTOM}$ | | 5.0 | | | A |
| EN Rising Threshold | $V_{ENH}$ | | 1.5 | | | V |
| EN Falling Threshold | $V_{ENL}$ | | | | 0.4 | V |
| Input UVLO Threshold | $V_{UVLO}$ | | | | 4.5 | V |
| UVLO Hysteresis | $V_{HYS}$ | | | 0.3 | | V |
| Min ON Time | | | | 80 | | ns |
| Min OFF Time | | | | 160 | | ns |
| Switching Frequency | | | | 500 | | kHz |
| Thermal Shutdown Temperature | $T_{SD}$ | | | 150 | | °C |
| Thermal Shutdown Hysteresis | $T_{HYS}$ | | | 15 | | °C |

**Note 1**: Stresses beyond the "Absolute Maximum Ratings" may cause permanent damage to the device. These are stress ratings only. Functional operation of the device at these or any other conditions beyond those indicated in the operational sections of the specificati n is not implied. Exposure to absolute maximum rating conditions for extended periods may affect device reliability.

**Note 2**: θJA is measured in the natural convection at $T_A$ = 25°C on a two-layer Silergy Evaluation Board..
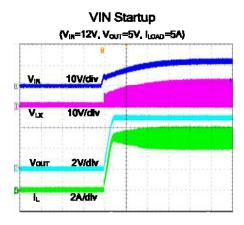
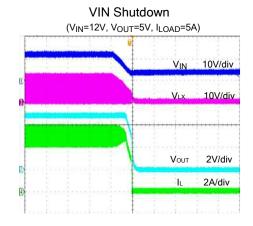**Note 3:** The device is not guaranteed to function outside its operating conditions
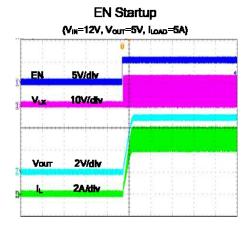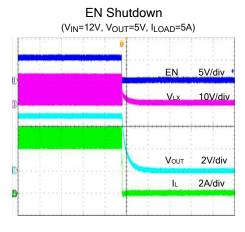
## Typical Performance Characteristics

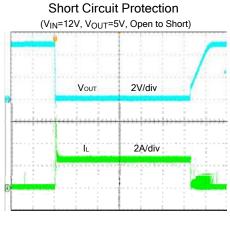### Efficiency vs. Load Current

Efficiency (%)

- —— $V_{IN}$=5V,$V_{OUT}$=1.2V
- --- $V_{IN}$=12V,$V_{OUT}$=1.2V
- --- $V_{IN}$=16V,$V_{OUT}$=1.2V

Load Current (A)

### Efficiency vs. Load Current

Efficiency (%)

- —— $V_{IN}$=5V,$V_{OUT}$=3.3V
- --- $V_{IN}$=12V,$V_{OUT}$=3.3V
- --- $V_{IN}$=16V,$V_{OUT}$=3.3V

Load Current (A)

### Efficiency vs. Load Current

Efficiency (%)

- —— $V_{IN}$=12V,$V_{OUT}$=5V
- --- $V_{IN}$=16V,$V_{OUT}$=5V

Load Current (A)

### Load Transient
($V_{IN}$=12V, $V_{OUT}$=5V, $I_{LOAD}$=0-2.5A)

$\Delta V_{OUT}$    200mV/div

$I_L$    1A/div

Time (100μs/div)

### Load Transient
($V_{IN}$=12V, $V_{OUT}$=5V, $I_{LOAD}$=0.5-5A)

$\Delta V_{OUT}$    500mV/div

$I_L$    2A/div

Time (100μs/div)

### Output Ripple
($V_{IN}$=12V, $V_{OUT}$=5V,$I_{LOAD}$=5A)

$\Delta V_{OUT}$    20mV/div

$V_{LX}$    10V/div

$I_L$    2A/div

Time (2μs/div)

### VIN Startup
(V$_{IN}$=12V, V$_{OUT}$=5V, I$_{LOAD}$=5A)

V$_{IN}$    10V/div

V$_{LX}$    10V/div

V$_{OUT}$    2V/div

I$_L$    2A/div

Time (2ms/div)

### VIN Shutdown
(V$_{IN}$=12V, V$_{OUT}$=5V, I$_{LOAD}$=5A)

V$_{IN}$    10V/div

V$_{LX}$    10V/div

V$_{OUT}$    2V/div

I$_L$    2A/div

Time (800µs/div)

### EN Startup
(V$_{IN}$=12V, V$_{OUT}$=5V, I$_{LOAD}$=5A)

EN    5V/div

V$_{LX}$    10V/div

V$_{OUT}$    2V/div

I$_L$    2A/div

Time (2ms/div)

### EN Shutdown
(V$_{IN}$=12V, V$_{OUT}$=5V, I$_{LOAD}$=5A)

EN    5V/div

V$_{LX}$    10V/div

V$_{OUT}$    2V/div

I$_L$    2A/div

Time (200µs/div)

### Short Circuit Protection
(V$_{IN}$=12V, V$_{OUT}$=5V, Open to Short)

V$_{OUT}$    2V/div

I$_L$    2A/div

Time (800us/div)

### Short Circuit Protection
(V$_{IN}$=12V, V$_{OUT}$=5V, 5A to Short)

V$_{OUT}$    2V/div

I$_L$    2A/div

Time (1ms/div)

## Operation

SY8105 is a synchronous buck regulator IC that integrates the PWM control, top and bottom switches on the same die to minimize the switching transition loss and conduction loss. With ultra low Rds(on) power switches and proprietary PWM control, this regulator IC can achieve the high efficiency and fast transient response. The high switching frequency allows using of small profile inductor and capacitor and the highest switch frequency simultaneously to minimize the external inductor and capacitor size, and thus achieving the minimum solution footprint.

## Applications Information

Because of the high integration in the SY8105 IC, the application circuit based on this regulator IC is rather simple. Only input capacitor $C_{IN}$, output capacitor $C_{OUT}$, output inductor L and feedback resistors ($R_1$ and $R_2$) need to be selected for the targeted applications specifications.

**Feedback resistor dividers R₁ and R₂**:
Choose $R_1$ and $R_2$ to program the proper output voltage. To minimize the power consumption under light loads, it is desirable to choose large resistance values for both $R_1$ and $R_2$. A value of between 10kΩ and 1MΩ s highly recommended for both resistors. If Vout is 3.3V, $R_1$=100k is chosen, then using following equatio , $R_2$ can be calculated to be 22.1k:

$$R_2 = \frac{0.6V}{V_{OUT} - 0.6V} R_1 .$$



**Input capacitor C_IN**:
The ripple current through input capacitor is calculated as：

$$I_{CIN\_RMS} = I_{OUT} \sqrt{D(1-D)} .$$

To minimize the potential noise problem, place a typical X5R or better grade ceramic capacitor really close to the IN and GND pins. Care should be taken to minimize the loop area formed by $C_{IN}$, and IN/GND pins. For most applications, a 10uF ceramic capacitor in parallel with 100nF 0603 size ceramic capacitor are recommended. And place the 100nF/0603 capacitor close to IC to attenuate high frequency noise.

**Output capacitor C_OUT:**
The output capacitor is selected to handle the output ripple noise requirements. Both steady state ripple and transient requirements must be taken into consideration when selecting this capacitor. For the best performance, it is recommended to use X5R or better grade ceramic capacitor greater than 47uF capacitance.

**Output inductor L:**
There are several considerations in choosing this inductor.

1) Choose the inductance to provide the desired ripple current. It is suggested to choose the ripple current to be about 40% of the maximum output current. The inductance is calculated as:

$$L = \frac{V_{OUT}(1 - V_{OUT}/V_{IN,MAX})}{F_{SW} \times I_{OUT,MAX} \times 40\%}$$

where Fsw is the switching frequency and $I_{OUT,MAX}$ is the maximum load current.
The SY8105 regulator IC is quite tolerant of different ripple current amplitude. Consequently, the final choice of inductance can be slightly off the calculation value without significantly impacting the performance.

2) The saturation current rating of the inductor must be selected to be greater than the peak inductor current under full load conditions.

$$I_{SAT,MIN} > I_{OUT,MAX} + \frac{V_{OUT}(1-V_{OUT}/V_{IN,MAX})}{2 \cdot F_{SW} \cdot L}$$

3) The DCR of the inductor and the core loss at the switching frequency must be low enough to achieve the desired efficiency requirement. It is desirable to choose an inductor with DCR<20mΩ to achieve a good overall efficiency.

**Soft-start**
The SY8105 has a built-in soft-start to control the rise rate of the output voltage and limit the input current surge during IC start-up. The typical soft-start time is 800us.
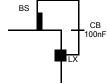
**Enable Operation**
Pulling the EN pin low (<0.4V) will shut down the device. During shutdown mode, the SY8105 shutdown current drops to lower than 5uA, Driving the EN pin high (>1.5V) will turn on the IC again.
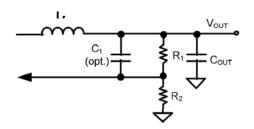
## External Bootstrap Cap

This capacitor provides the gate driver voltage for internal high side MOSEFET. A 100nF low ESR ceramic capacitor connected between BS pin and LX pin is recommended.
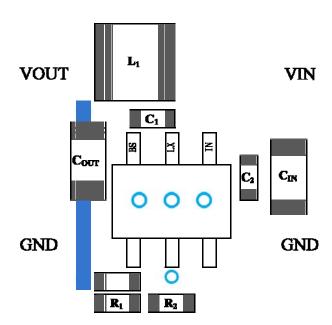
BS

CB
100nF

LX

## Load Transient Considerations:

The SY8105 regulator IC integrates the compensation components to achieve good stability and fast transient responses. In some applications, adding a small ceramic cap in parallel with R1 may further speed up the load transient responses and is thus recommended for applications with large load transient step requirements.

L

$V_{OUT}$

$C_1$
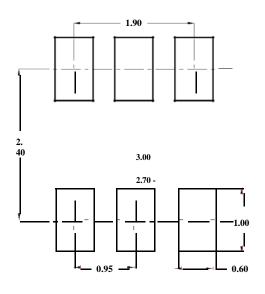(opt.)

$R_1$  $C_{OUT}$

$R_2$

## Layout Design:

The layout design of SY8105 regulator is relatively simple. For the best efficiency and minimum noise problem, we should place the following components close to the IC: CIN, L, R1 and R2.
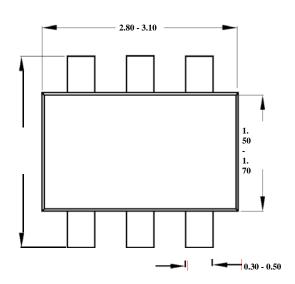
1) It is desirable to maximize the PCB copper area connecting to GND pin to achieve the best thermal and noise performance. If the board space allowed, a ground plane is highly desirable.

2) $C_{IN}$ must be close to Pins IN and GND. The loop area formed by $C_{IN}$ and GND must be minimized.

3) The PCB copper area associated with LX pin must be minimized to avoid the potential noise problem.

4) The components $R_1$ and $R_2$, and the trace connecting to the FB pin must NOT be adjacent to the LX net on the PCB layout to avoid the noise problem.

5) If the system chip interfacing with the EN pin has a high impedance state at shutdown mode and the IN pin is connected directly to a power source such as a Li-Ion battery, it is desirable to add a pull down 1Mohm resistor between the EN and GND pins to prevent the noise from falsely turning on the regulator at shutdown mode.
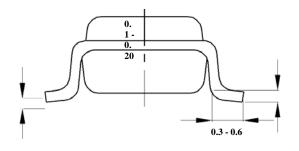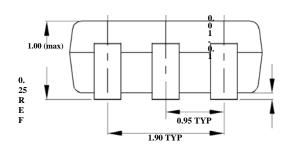
VOUT     $L_1$     VIN

$C_1$

BS   LX   IN

$C_{OUT}$

$C_2$   $C_{IN}$

GND     GND

$R_1$   $R_2$

# TSOT23-6L (FC)Package outline & PCB layout

1.90

2.80 - 3.10

2.40

3.00

2.70 -

1.50 - 1.70

1.00

0.95          0.60

0.30 - 0.50

**Recommended Pad Layout**

0.1 - 0.20

0.3 - 0.6

1.00 (max)

0.01 - 0.1

0.25 REF

0.95 TYP

1.90 TYP

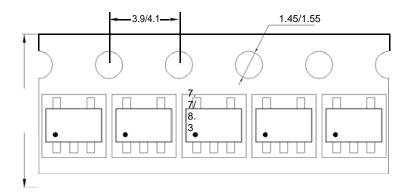**Notes:**      **All dimension in MM**
**All dimension don't not include mold flash & metal burr**

# Taping & Reel Specification

## 1. Taping orientation

TSOT23-6

3.9/4.1    1.45/1.55

7.
7/
8.
3

**Feeding direction** ⟶

## 2. Carrier Tape & Reel specification for packages

Reel
Width

Reel
Size

| Package types | Tape width (mm) | Pocket pitch(mm) | Reel size (Inch) | Reel width(mm) | Trailer length(mm) | Leader length (mm) | Qty per reel |
|---|---|---|---|---|---|---|---|
| TSOT23-6 | 8 | 4 | 7'' | 8.4 | 280 | 160 | 3000 |

## 3. Others: NA